

LM236-2.5, LM336-2.5, LM336B-2.5 2.5-V INTEGRATED REFERENCE CIRCUITS

SLVS063E – NOVEMBER 1988 – REVISED OCTOBER 2003

- Low Temperature Coefficient
- Wide Operating Current . . . 400 μ A to 10 mA
- 0.27- Ω Dynamic Impedance
- \pm 1% Tolerance Available
- Specified Temperature Stability
- Easily Trimmed for Minimum Temperature Drift
- Fast Turnon

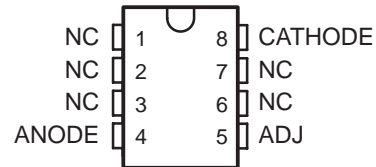
description/ordering information

The LM236-2.5, LM336-2.5, and LM336B-2.5 integrated circuits are precision 2.5-V shunt regulator diodes. These reference circuits operate as low-temperature-coefficient 2.5-V Zener diodes with a 0.2- Ω dynamic impedance. A third terminal provided on the circuit allows the reference voltage and temperature coefficient to be trimmed easily.

The series is useful as precision 2.5-V low-voltage references (V_Z) for digital voltmeters, power supplies, or operational-amplifier circuitry. The 2.5-V voltage reference makes it convenient to obtain a stable reference from 5-V logic supplies. Devices in this series operate as shunt regulators, and can be used as either positive or negative voltage references.

The LM236-2.5 is characterized for operation from -25°C to 85°C . The LM336-2.5 and LM336B-2.5 are characterized for operation from 0°C to 70°C .

D PACKAGE
(TOP VIEW)



NC – No internal connection

LM336-2.5, LM336B-2.5 . . . LP PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (D)	Tube of 75	LM336D-2-5	336-25
		Reel of 2500	LM336DR-2-5	
		Tube of 75	LM336BD-2-5	336B25
		Reel of 2500	LM336BDR-2-5	
	TO-226 / TO-92 (LP)	Bulk of 1000	LM336LP-2-5	336-25
		Reel of 2000	LM336LPR-2-5	
		Bulk of 1000	LM336BLP-2-5	336B25
		Reel of 2000	LM336BLPR-2-5	
-25°C to 85°C	SOIC (D)	Tube of 75	LM236D-2-5	236-25
		Reel of 2500	LM236DR-2-5	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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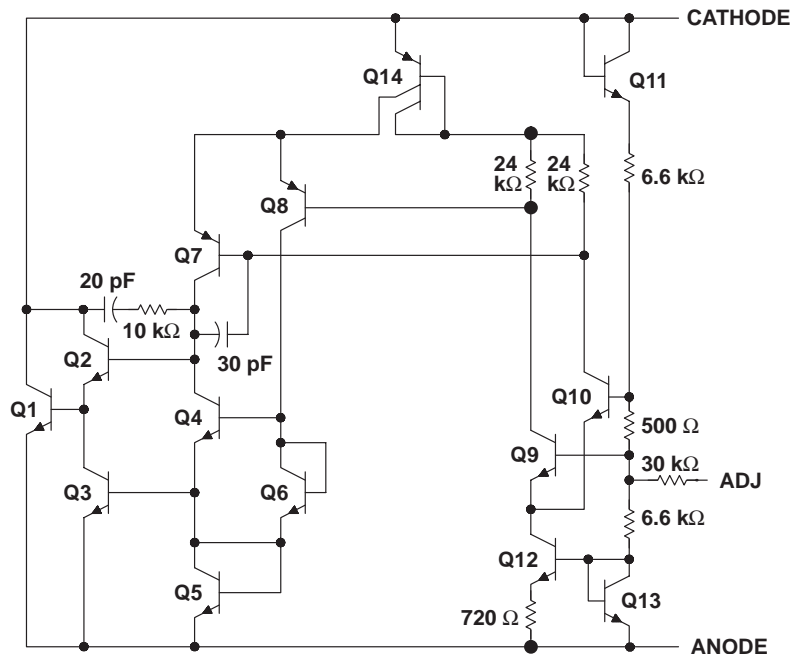
LM236-2.5, LM336-2.5, LM336B-2.5 2.5-V INTEGRATED REFERENCE CIRCUITS

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symbol



schematic diagram



NOTE A: All component values are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Reverse current, I_R	20 mA
Forward current, I_F	10 mA
Package thermal impedance, θ_{JA} (see Notes 1 and 2): D package	97°C/W
LP package	140°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
T_A Operating free-air temperature	LM236-2.5	-25	85	°C
	LM336-2.5, LM336B-2.5	0	70	



LM236-2.5, LM336-2.5, LM336B-2.5 2.5-V INTEGRATED REFERENCE CIRCUITS

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electrical characteristics at specified free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T_A †	LM236-2.5			LM336-2.5			UNIT			
			MIN	TYP	MAX	MIN	TYP	MAX				
V_Z Reference voltage	$I_Z = 1 \text{ mA}$	25°C	LM236, LM336			2.44	2.49	2.54	2.39	2.49	2.59	V
			LM336B						2.44	2.49	2.54	
$\Delta V_Z(\Delta T)$ Change in reference voltage with temperature	V_Z adjusted to 2.490 V, $I_Z = 1 \text{ mA}$	Full range		3.5	9		1.8	6			mV	
$\Delta V_Z(\Delta I)$ Change in reference voltage with current	$I_Z = 400 \mu\text{A}$ to 10 mA	25°C		2.6	6		2.6	10			mV	
		Full range		3	10		3	12				
$\Delta V_Z(\Delta t)$ Long-term change in reference voltage	$I_Z = 1 \text{ mA}$	25°C		20			20				ppm/khr	
z_z Reference impedance	$I_Z = 1 \text{ mA}$, $f = 1 \text{ kHz}$	25°C		0.2	0.6		0.2	1			W	
		Full range		0.4	1		0.4	1.4				

† Full range is –25°C to 85°C for the LM236-2.5 and 0°C to 70°C for the LM336-2.5 and LM336B-2.5.

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TYPICAL CHARACTERISTICS

CHANGE IN REFERENCE VOLTAGE
vs
REFERENCE CURRENT

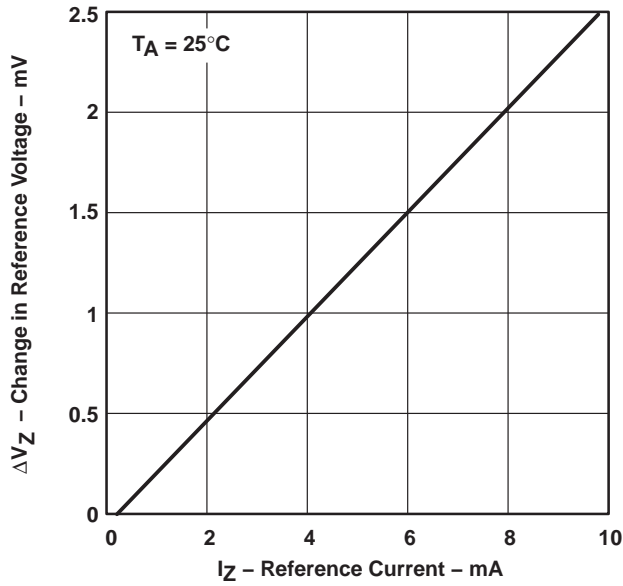


Figure 1

NOISE VOLTAGE
vs
FREQUENCY

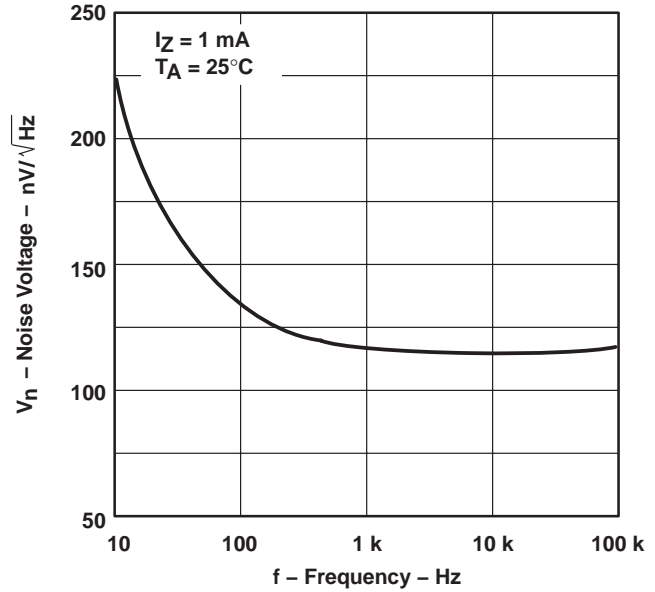


Figure 2

REFERENCE IMPEDANCE
vs
FREQUENCY

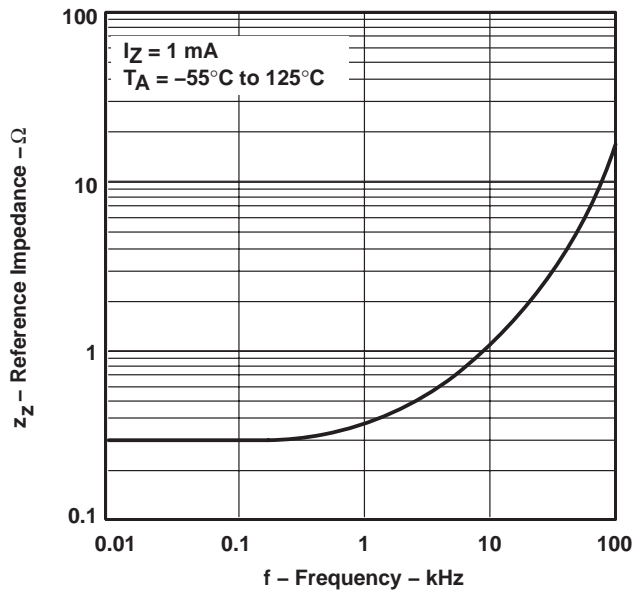


Figure 3

APPLICATION INFORMATION

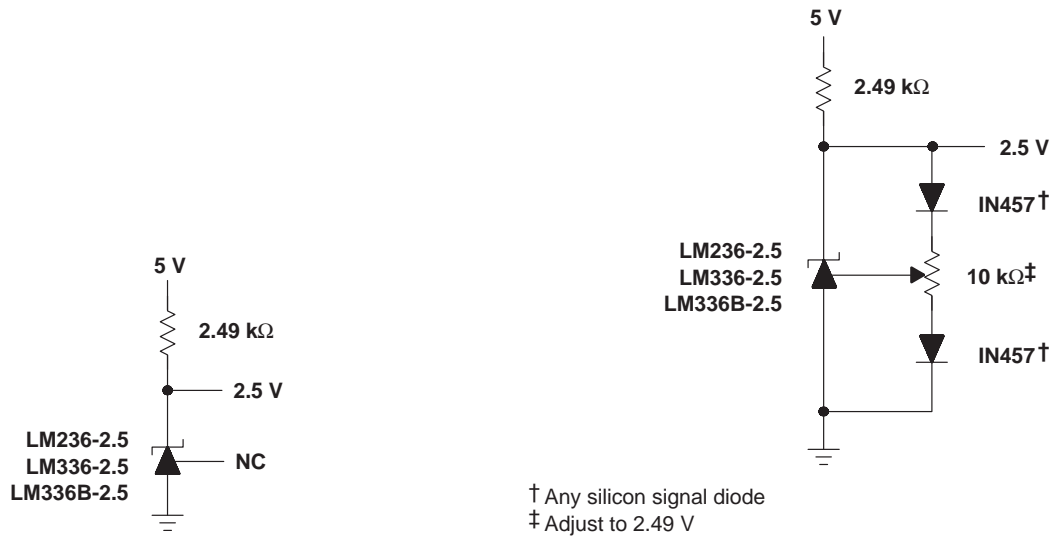


Figure 4. 2.5-V Reference

Figure 5. 2.5-V Reference With Minimum Temperature Coefficient

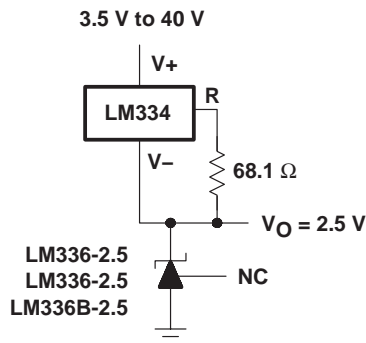


Figure 6. Wide-Input-Range Reference

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM236D-2-5	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	236-25
LM236D-2-5.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	236-25
LM236DR-2-5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	236-25
LM236DR-2-5.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	236-25
LM336-2.5 MDC	Active	Production	DIESALE (Y) 0	400 NOT REQUIRED	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LM336BD-2-5	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336B25
LM336BD-2-5.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336B25
LM336BDR-2-5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336B25
LM336BDR-2-5.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336B25
LM336BLP-2-5	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	0 to 70	336B25
LM336BLP-2-5.A	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	0 to 70	336B25
LM336BLPR-2-5	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	336B25
LM336BLPR-2-5.A	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	336B25
LM336D-2-5	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336-25
LM336D-2-5.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336-25
LM336DR-2-5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336-25
LM336DR-2-5.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	336-25
LM336LP-2-5	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	0 to 70	336-25
LM336LP-2-5.A	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	0 to 70	336-25
LM336LPR-2-5	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	336-25
LM336LPR-2-5.A	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	336-25

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM236DR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM336BDR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM336DR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM236DR-2-5	SOIC	D	8	2500	353.0	353.0	32.0
LM336BDR-2-5	SOIC	D	8	2500	353.0	353.0	32.0
LM336DR-2-5	SOIC	D	8	2500	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LM236D-2-5	D	SOIC	8	75	507	8	3940	4.32
LM236D-2-5.A	D	SOIC	8	75	507	8	3940	4.32
LM336BD-2-5	D	SOIC	8	75	507	8	3940	4.32
LM336BD-2-5.A	D	SOIC	8	75	507	8	3940	4.32
LM336D-2-5	D	SOIC	8	75	507	8	3940	4.32
LM336D-2-5.A	D	SOIC	8	75	507	8	3940	4.32



D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed $.006$ [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
 EXPOSED METAL SHOWN
 SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

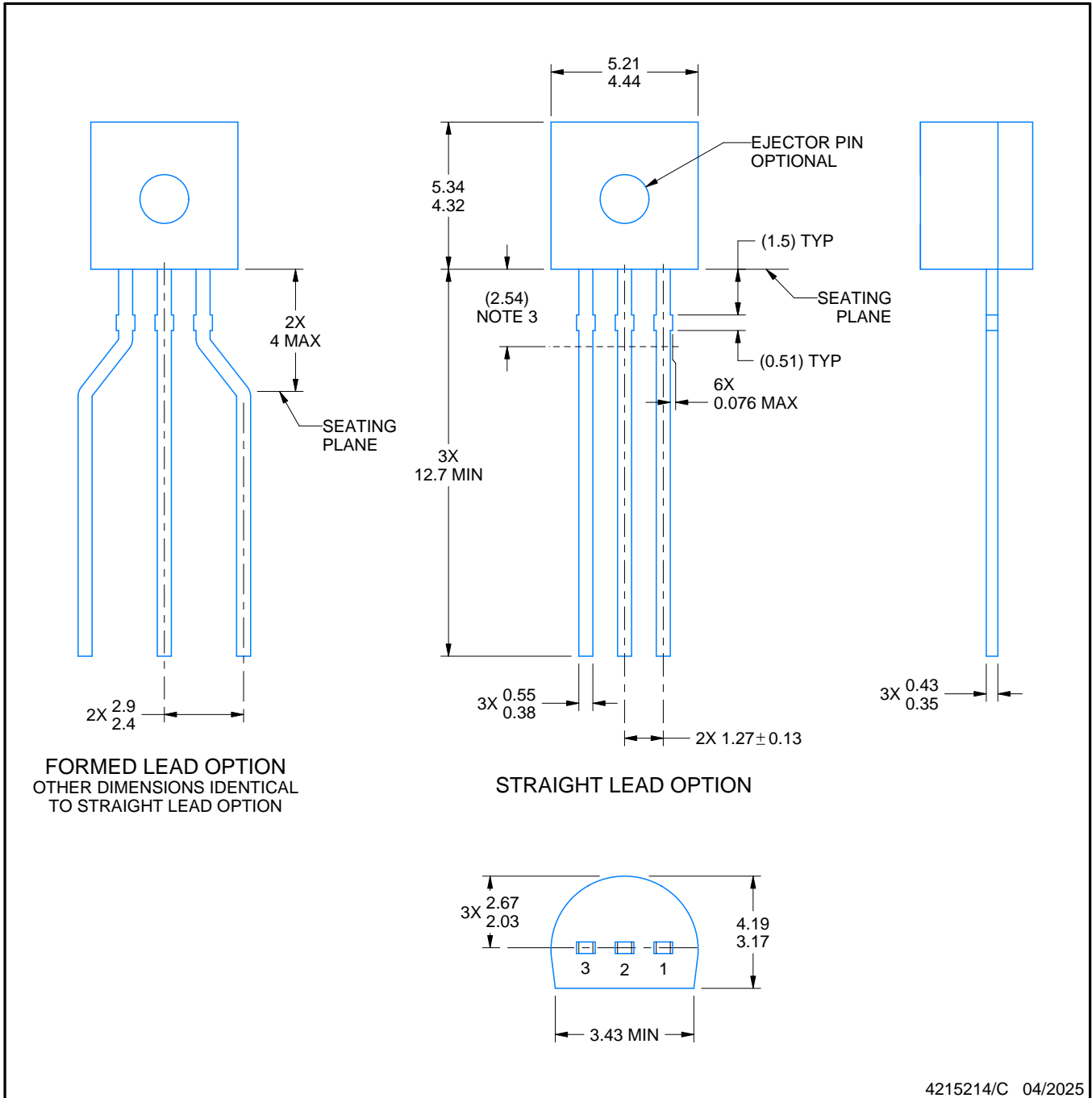
LP0003A



PACKAGE OUTLINE

TO-92 - 5.34 mm max height

TO-92



4215214/C 04/2025

NOTES:

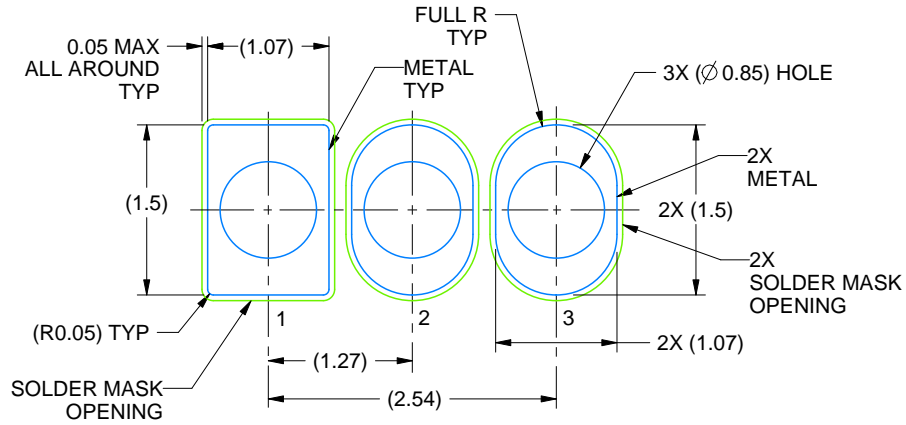
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
 - a. Straight lead option available in bulk pack only.
 - b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.

EXAMPLE BOARD LAYOUT

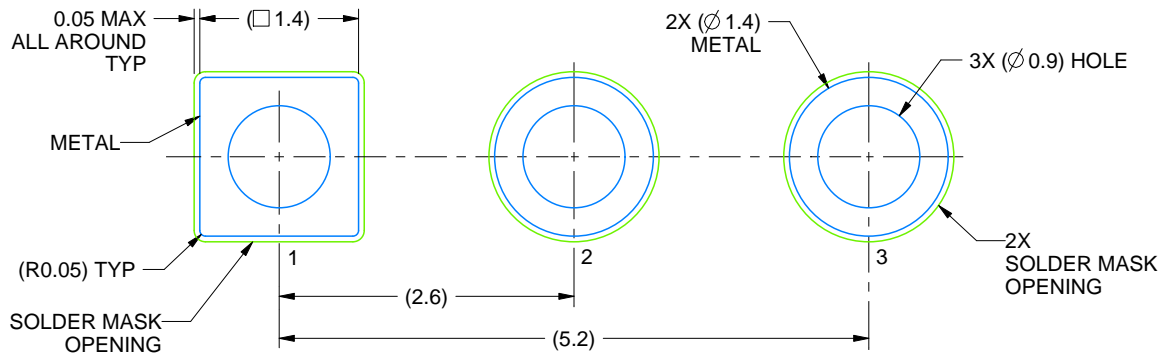
LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

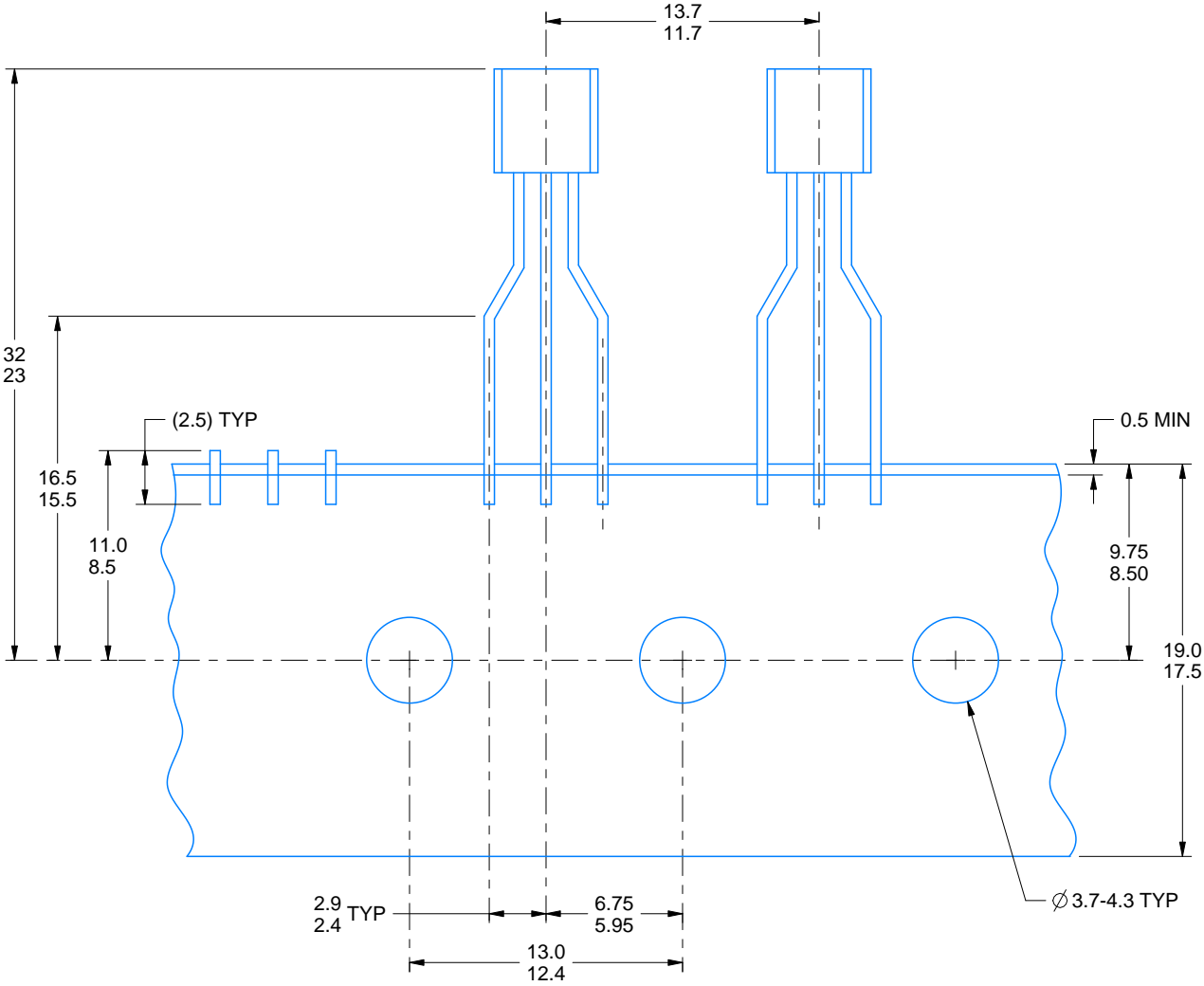
4215214/C 04/2025

TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/C 04/2025

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